

filling a solder resist or resin in spaces between the first circuit patterns;

grinding the surface of the board; and

performing a two dimensional plating on an upper surface of the first pattern.

36. The method of claim 35, wherein the two dimensional plating is a gold plating.

37. A method for manufacturing a printed circuit board having a plurality of circuit patterns formed on a surface of the board and formed in the board and a plurality of holes for electrically connecting the circuit patterns, comprising the steps of:

filling a solder resist or resin in spaces between the circuit patterns formed on the surface of the board;

grinding the surface of the board and exposing an upper surface of the circuit patterns formed on the surface of the board; and

performing a two dimensional plating on the exposed upper surface of the circuit pattern formed on the surface of the board.

38. The method of claim 37, wherein the two dimensional
plating is a gold plating.

AdB